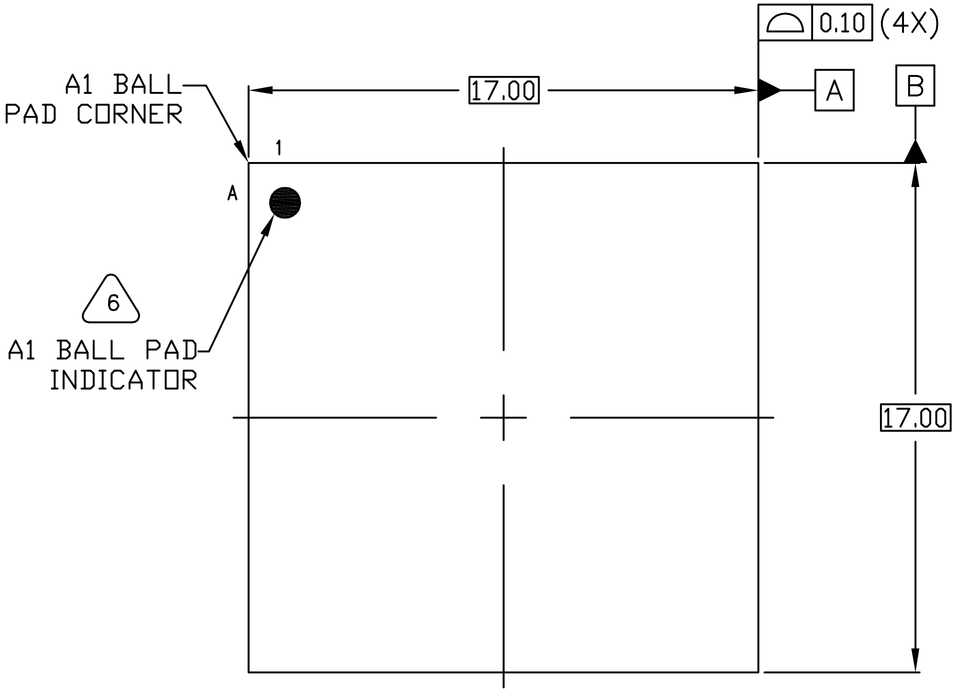
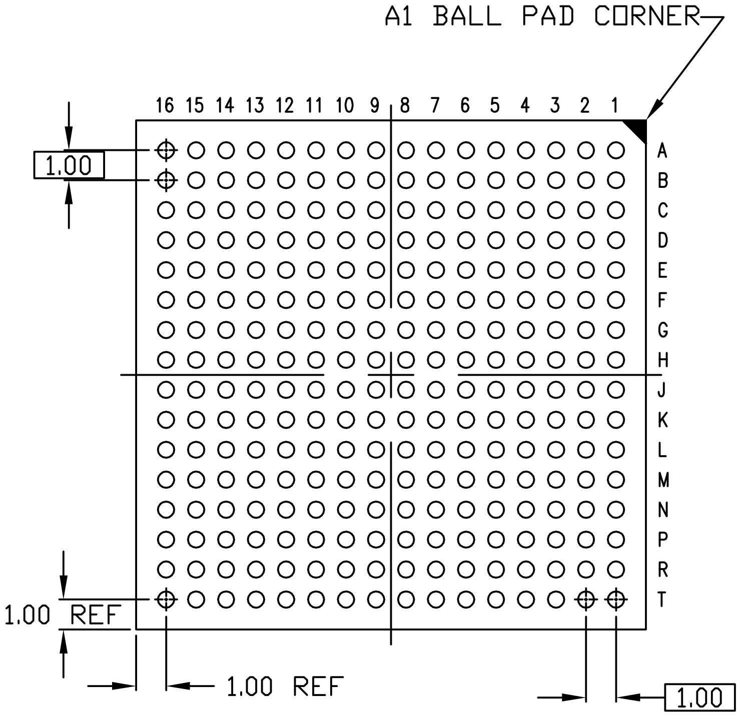
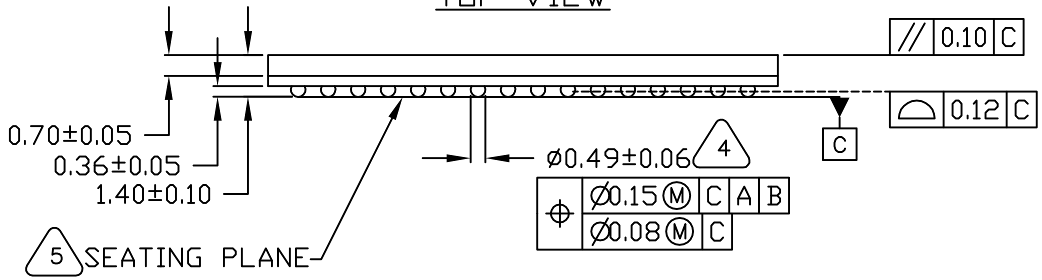


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
5. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
8. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131
9. PACKAGE CODES: X256-2

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE, 256 BALLS CSBGA,
17x17mm, 1.00mm PITCH, 2 LAYER

APPROVAL	DOCUMENT CONTROL NO.	REV.	
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